Materials Declaration

Package	CerDIP
Body Size	600 mils
Lead Count	24
Option	SnPb

Base

Substance	% of Base	Weight (g)	PPM
Ceramics			
Aluminum Oxide	70.25	1.69 E+00	248378
Manganese Dioxide	2.66	6.38 E-02	9405
Silicon Dioxide	2.30	5.52 E-02	8132
Titanium Dioxide	1.50	3.60 E-02	5303
Chromium Oxide	1.10	2.64 E-02	3889
Iron Oxide	0.90	2.16 E-02	3182
Magnesium Oxide	0.40	9.60 E-03	1414
Cobalt Oxide	0.20	4.80 E-03	707
Calcium Oxide	0.03	7.20 E-04	106
Subtotal	79.34	1.90 E+00	280516
Sealing Glass			
Lead Oxide	12.55	3.01 E-01	44372
Tin Oxide	3.30	7.92 E-02	11668
Silicon Dioxide	1.50	3.60 E-02	5303
Boron Trioxide	1.20	2.88 E-02	4243
Aluminum Oxide	0.80	1.92 E-02	2828
Titanium Dioxide	0.50	1.20 E-02	1768
Magnesium Oxide	0.50	1.20 E-02	1768
Zinc Oxide	0.20	4.80 E-03	707
Calcium Oxide	0.05	1.20 E-03	177
Iron Oxide	0.03	7.20 E-04	106
Chromium Oxide	0.02	4.80 E-04	71
Manganese Dioxide	0.01	2.40 E-04	35
Sodium Oxide	0.002	4.80 E-05	7
Subtotal	20.662	4.96 E-01	73053
Total	100.00	2.40 E+00	353569

Caps

Substance	% of Caps	Weight (g)	PPM
Ceramics			
Aluminum Oxide	63.90	1.73 E+00	254167
Manganese Dioxide	2.40	6.48 E-02	9546
Silicon Dioxide	2.10	5.67 E-02	8353
Titanium Dioxide	1.30	3.51 E-02	5171
Chromium Oxide	1.00	2.70 E-02	3978
Iron Oxide	0.80	2.16 E-02	3182
Magnesium Oxide	0.40	1.08 E-02	1591
Cobalt Oxide	0.20	5.40 E-03	796
Calcium Oxide	0.03	8.10 E-04	119
Subtotal	72.13	1.95 E+00	286903
Sealing glass			
Lead oxide	17.00	4.59 E-01	67619
Tin oxide	4.50	1.22 E-01	17899
Silicon dioxide	2.03	5.48 E-02	8074
Boron Trioxide	1.60	4.32 E-02	6364
Aluminum oxide	1.10	2.97 E-02	4375
Magnesium oxide	0.60	1.62 E-02	2387
Titanium Dioxide	0.70	1.89 E-02	2784
Calcium oxide	0.06	1.62 E-03	239
Zinc oxide	0.20	5.40 E-03	796
Chromium oxide	0.03	8.10 E-04	119
Iron oxide	0.04	1.08 E-03	159
Manganese dioxide	0.01	2.70 E-04	40
Sodium Oxide	0.003	8.10 E-05	12
Subtotal	27.87	7.52 E-01	110855
Total	100.00	2.70 E+00	397758

Leadframe

Substance	% of Leadframe	Weight (g)	PPM
Iron	58.45	3.51 E-01	51664
Nickel	40.84	2.45 E-01	36099
Manganese	0.52	3.12 E-03	460
Silicon	0.13	7.80 E-04	115
Cobalt	0.03	1.80 E-04	27
Aluminum	0.01	6.00 E-05	9
Chromium	0.01	6.00 E-05	9
Sulfur	0.01	3.60 E-05	5
Carbon	0.003	1.80 E-05	3
Phosphorus	0.002	1.20 E-05	2
Subtotal	100.00	6.00 E-01	88391

Paste

Substance	% of Paste	Weight (g)	PPM
Silver	80	1.44 E-02	2121
Lead Borate Glass	20	3.60 E-03	530
Subtotal	100	1.80 E-02	2652

Chip

Substance	% of Chip	Weight (g)	PPM
Doped Silicon	100	6.67 E-01	98261

Bonding Wires

Substance	% of Wire	Weight (g)	PPM
Aluminum	100	1.80 E-02	2652

External Leadframe Plating

Substance	% of Plating	Weight (g)	PPM
Tin	63	2.43 E-01	35732
Lead	37	1.42 E-01	20985
Subtotal	100	3.85 E-01	56717

Package Totals

Weight (g)	PPM
6.79 E+00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability
any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary